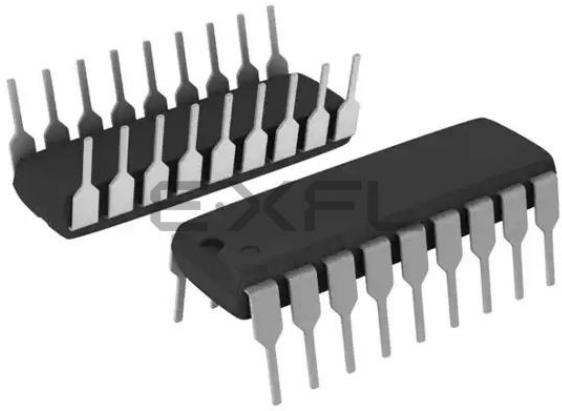

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	16
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf1330-i-p

18/20/28-Pin Enhanced Flash Microcontrollers with nanoWatt Technology, High-Performance PWM and A/D

Power-Managed Modes:

- Run: CPU on, peripherals on
- Idle: CPU off, peripherals on
- Sleep: CPU off, peripherals off
- Ultra Low 50 nA Input Leakage
- Run mode currents down to 15 μA, typical
- Idle mode currents down to 3.7 μA, typical
- Sleep mode current down to 100 nA, typical
- Timer1 Oscillator: 1.8 μA, typical; 32 kHz; 2V
- Watchdog Timer (WDT): 1.4 μA, typical; 2V
- Two-Speed Oscillator Start-up

14-Bit Power Control PWM Module:

- Up to 6 PWM Channel Outputs
  - Complementary or independent outputs
- Edge or Center-Aligned Operation
- Flexible Dead-Band Generator
- Hardware Fault Protection Input
- Simultaneous Update of Duty Cycle and Period:
  - Flexible Special Event Trigger output

Flexible Oscillator Structure:

- Four Crystal modes, up to 40 MHz
- 4x Phase Lock Loop (PLL) – Available for Crystal and Internal Oscillators
- Two External RC modes, up to 4 MHz
  - Fast wake-up from Sleep and Idle, 1 μs, typical
- Two External Clock modes, up to 40 MHz
- Internal Oscillator Block:
  - 8 user-selectable frequencies from 31 kHz to 8 MHz
  - Provides a complete range of clock speeds from 31 kHz to 32 MHz when used with PLL
  - User-tunable to compensate for frequency drift
- Secondary Oscillator using Timer1 @ 32 kHz
- Fail-Safe Clock Monitor:
  - Allows for safe shutdown if peripheral clock stops

Peripheral Highlights:

- High-Current Sink/Source 25 mA/25 mA
- Up to 4 Programmable External Interrupts
- Four Input Change Interrupts
- Enhanced Addressable USART module:
  - Supports RS-485, RS-232 and LIN/J2602
  - RS-232 operation using internal oscillator block (no external crystal required)
  - Auto-wake-up on Start bit
  - Auto-Baud Detect
- 10-Bit, up to 4-Channel Analog-to-Digital Converter module (A/D):
  - Auto-acquisition capability
  - Conversion available during Sleep
- Up to 3 Analog Comparators
- Programmable Reference Voltage for Comparators
- Programmable, 15-Level Low-Voltage Detection (LVD) module:
  - Supports interrupt on Low-Voltage Detection

Special Microcontroller Features:

- C Compiler Optimized Architecture with Optional Extended Instruction Set
- Flash Memory Retention: > 40 years
- Self-Programmable under Software Control
- Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 4 ms to 131s
- Programmable Code Protection
- Single-Supply In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug (ICD) via Two Pins
- Wide Operating Voltage Range (2.0V to 5.5V)

Device	Program Memory		Data Memory		I/O	10-Bit ADC Channel	EUSART	Analog Comparator	14-Bit PWM (ch)	Timers 16-Bit
	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)						
PIC18F1230	4096	2048	256	128	16	4	Yes	3	6	2
PIC18F1330	8192	4096	256	128	16	4	Yes	3	6	2

TABLE 1-1: DEVICE FEATURES

Features	PIC18F1230	PIC18F1330
Operating Frequency	DC – 40 MHz	DC – 40 MHz
Program Memory (Bytes)	4096	8192
Program Memory (Instructions)	2048	4096
Data Memory (Bytes)	256	256
Data EEPROM Memory (Bytes)	128	128
Interrupt Sources	17	17
I/O Ports	Ports A, B	Ports A, B
Timers	2	2
Power Control PWM Module	6 Channels	6 Channels
Serial Communications	Enhanced USART	Enhanced USART
10-Bit Analog-to-Digital Module	4 Input Channels	4 Input Channels
Resets (and Delays)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{MCLR}$ (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{MCLR}$ (optional), WDT
Programmable Low-Voltage Detect	Yes	Yes
Programmable Brown-out Reset	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set enabled	75 Instructions; 83 with Extended Instruction Set enabled
Packages	18-Pin PDIP 18-Pin SOIC 20-Pin SSOP 28-Pin QFN	18-Pin PDIP 18-Pin SOIC 20-Pin SSOP 28-Pin QFN

TABLE 1-2: PIC18F1230/1330 PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP, SOIC	SSOP	QFN			
MCLR/VPP/RA5/FLTA	4	4	1			Master Clear (input), programming voltage (input) or Fault detect input.
MCLR				I	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
VPP				I	Analog	Programming voltage input.
RA5				I	ST	Digital input.
FLTA(1)				I	ST	Fault detect input for PWM.
RA7/OSC1/CLKI/ T1OSI/FLTA	16	18	21			Oscillator crystal, external clock input, Timer1 oscillator input or Fault detect input.
RA7				I/O	ST	Digital I/O.
OSC1				I	Analog	Oscillator crystal input or external clock source input.
CLKI				I	—	External clock source input.
T1OSI(2)				I	Analog	Timer1 oscillator input.
FLTA(1)				I	ST	Fault detect input for PWM.
RA6/OSC2/CLKO/ T1OSO/T1CKI/AN3	15	17	20			Oscillator crystal, clock output, Timer1 oscillator output or analog input.
RA6				I/O	ST	Digital I/O.
OSC2				O	—	Oscillator crystal output or external clock source input.
CLKO				O	—	External clock source output.
T1OSO(2)				O	—	Timer1 oscillator output.
TICKI(2)				I	ST	Timer1 clock input.
AN3				I	Analog	Analog input 3.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Placement of FLTA depends on the value of Configuration bit, FLTAMX, of CONFIG3H.

2: Placement of T1OSI and T1OSO/T1CKI depends on the value of Configuration bit, T1OSCMX, of CONFIG3H.

TABLE 1-2: PIC18F1230/1330 PINOUT I/O DESCRIPTIONS (CONTINUED)

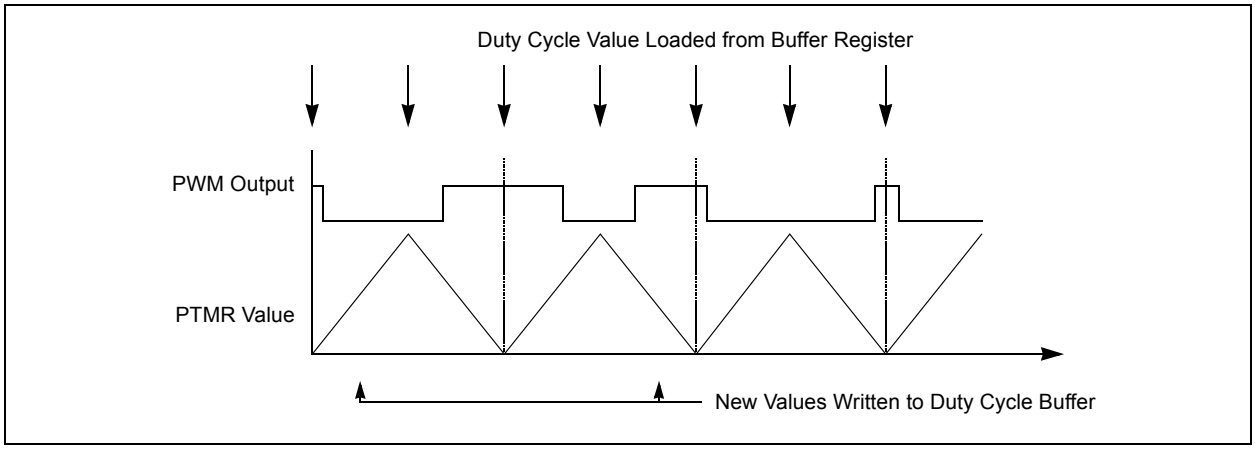
Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP, SOIC	SSOP	QFN			
						PORTB is a bidirectional I/O port.
RB0/PWM0	8	9	9			
RB0				I/O	TTL	Digital I/O.
PWM0				O	—	PWM module output PWM0.
RB1/PWM1	9	10	10			
RB1				I/O	TTL	Digital I/O.
PWM1				O	—	PWM module output PWM1.
RB2/INT2/KBI2/CMP2/ T1OSO/T1CKI	17	19	23			
RB2				I/O	TTL	Digital I/O.
INT2				I	ST	External interrupt 2.
KBI2				I	TTL	Interrupt-on-change pin.
CMP2				I	Analog	Comparator 2 input.
T1OSO(2)				O	—	Timer1 oscillator output.
T1CKI(2)				I	ST	Timer1 clock input.
RB3/INT3/KBI3/CMP1/ T1OSI	18	20	24			
RB3				I/O	TTL	Digital I/O.
INT3				I	ST	External interrupt 3.
KBI3				I	TTL	Interrupt-on-change pin.
CMP1				I	Analog	Comparator 1 input.
T1OSI(2)				I	Analog	Timer1 oscillator input.
RB4/PWM2	10	11	12			
RB4				I/O	TTL	Digital I/O.
PWM2				O	—	PWM module output PWM2.
RB5/PWM3	11	12	13			
RB5				I/O	TTL	Digital I/O.
PWM3				O	—	PWM module output PWM3.
RB6/PWM4/PGC	12	13	15			
RB6				I/O	TTL	Digital I/O.
PWM4				O	—	PWM module output PWM4.
PGC				I	ST	In-Circuit Debugger and ICSP™ programming clock pin.
RB7/PWM5/PGD	13	14	16			
RB7				I/O	TTL	Digital I/O.
PWM5				O	—	PWM module output PWM5.
PGD				O	—	In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Placement of $\overline{\text{FLTA}}$ depends on the value of Configuration bit, FLTAMX, of CONFIG3H.

2: Placement of T1OSI and T1OSO/T1CKI depends on the value of Configuration bit, T1OSCMX, of CONFIG3H.

FIGURE 14-14: DUTY CYCLE UPDATE TIMES IN CONTINUOUS UP/DOWN COUNT MODE WITH DOUBLE UPDATES

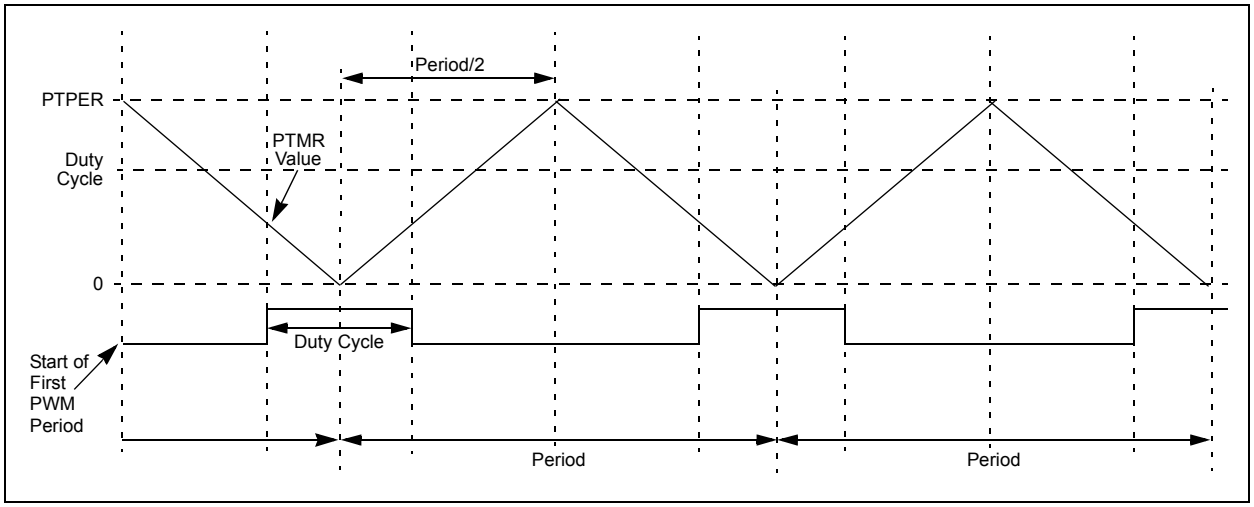


14.6.4 CENTER-ALIGNED PWM

Center-aligned PWM signals are produced by the module when the PWM time base is configured in a Continuous Up/Down Count mode (see Figure 14-15). The PWM compare output is driven to the active state when the value of the Duty Cycle register matches the value of PTMR and the PWM time base is counting downwards (PTDIR = 1). The PWM compare output will be driven to the inactive state when the PWM time base is counting upwards (PTDIR = 0) and the value in the PTMR register matches the duty cycle value. If the value in a particular Duty Cycle register is zero, then the output on the corresponding PWM pin will be inactive for the entire PWM period. In addition, the output on the PWM pin will be active for the entire PWM period if the value in the Duty Cycle register is equal to or greater than the value in the PTPER register.

Note:	When the PWM is started in Center-Aligned mode, the PWM Time Base Period register (PTPER) is loaded into the PWM Time Base register (PTMR) and the PTMR is configured automatically to start down counting. This is done to ensure that all the PWM signals don't start at the same time.

FIGURE 14-15: START OF CENTER-ALIGNED PWM



REGISTER 14-5: DTCON: DEAD-TIME CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DTPS1	DTPS0	DT5	DT4	DT3	DT2	DT1	DT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **DTPS1:DTPS0:** Dead-Time Unit A Prescale Select bits
11 = Clock source for dead-time unit is FOSC/16
10 = Clock source for dead-time unit is FOSC/8
01 = Clock source for dead-time unit is FOSC/4
00 = Clock source for dead-time unit is FOSC/2

bit 5-0 **DT5:DT0:** Unsigned 6-Bit Dead-Time Value for Dead-Time Unit bits

14.7.2 DEAD-TIME RANGES

The amount of dead time provided by the dead-time unit is selected by specifying the input clock prescaler value and a 6-bit unsigned value defined in the DTCON register. Four input clock prescaler selections have been provided to allow a suitable range of dead times based on the device operating frequency. FOSC/2, FOSC/4, FOSC/8 and FOSC/16 are the clock prescaler options available using the DTPS1:DTPS0 control bits in the DTCON register.

After selecting an appropriate prescaler value, the dead time is adjusted by loading a 6-bit unsigned value into DTCON<5:0>. The dead-time unit prescaler is cleared on any of the following events:

- On a load of the down timer due to a duty cycle comparison edge event;
- On a write to the DTCON register; or
- On any device Reset.

14.7.3 DECREMENTING THE DEAD-TIME COUNTER

The dead-time counter is clocked from any of the Q clocks based on the following conditions.

1. The dead-time counter is clocked on Q1 when:
   - The DTPS bits are set to any of the following dead-time prescaler settings: FOSC/4, FOSC/8, FOSC/16
   - The PWM Time Base Prescale bits (PTCKPS<1:0>) are set to any of the following prescale ratios: FOSC/16, FOSC/64, FOSC/256
2. The dead-time counter is clocked by a pair of Q clocks when the PWM Time Base Prescale bits are set to 1:1 (PTCKPS<1:0> = 00, FOSC/4) and the dead-time counter is clocked by the FOSC/2 (DTPS<1:0> = 00).
3. The dead-time counter is clocked using every other Q clock, depending on the two LSbs in the Duty Cycle registers:
   - If the PWM duty cycle match occurs on Q1 or Q3, then the dead-time counter is clocked using every Q1 and Q3
   - If the PWM duty cycles match occurs on Q2 or Q4, then the dead-time counter is clocked using every Q2 and Q4
4. When the DTPS<1:0> bits are set to any of the other dead-time prescaler settings (i.e., FOSC/4, FOSC/8 or FOSC/16) and the PWM time base prescaler is set to 1:1, the dead-time counter is clocked by the Q clock corresponding to the Q clocks on which the PWM duty cycle match occurs.

NOTES:

15.1 Baud Rate Generator (BRG)

The BRG is a dedicated 8-bit or 16-bit generator that supports both the Asynchronous and Synchronous modes of the EUSART. By default, the BRG operates in 8-bit mode; setting the BRG16 bit (BAUDCON<3>) selects 16-bit mode.

The SPBRGH:SPBRG register pair controls the period of a free-running timer. In Asynchronous mode, bits BRGH (TXSTA<2>) and BRG16 (BAUDCON<3>) also control the baud rate. In Synchronous mode, BRGH is ignored. Table 15-1 shows the formula for computation of the baud rate for different EUSART modes which only apply in Master mode (internally generated clock).

Given the desired baud rate and FOSC, the nearest integer value for the SPBRGH:SPBRG registers can be calculated using the formulas in Table 15-1. From this, the error in baud rate can be determined. An example calculation is shown in Example 15-1. Typical baud rates and error values for the various Asynchronous modes are shown in Table 15-2. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG to reduce the baud rate error, or achieve a slow baud rate for a fast oscillator frequency.

Writing a new value to the SPBRGH:SPBRG registers causes the BRG timer to be reset (or cleared). This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

Note:	A BRG value of '0' is not supported.

15.1.1 OPERATION IN POWER-MANAGED MODES

The device clock is used to generate the desired baud rate. When one of the power-managed modes is entered, the new clock source may be operating at a different frequency. This may require an adjustment to the value in the SPBRG register pair.

15.1.2 SAMPLING

The data on the RX pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin when SYNC is clear or when both BRG16 and BRGH are not set. The data on the RX pin is sampled once when SYNC is set or when BRGH16 and BRGH are both set.

TABLE 15-1: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n + 1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n + 1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n + 1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH:SPBRG register pair

15.4 EUSART Synchronous Slave Mode

Synchronous Slave mode is entered by clearing bit, CSRC (TXSTA<7>). This mode differs from the Synchronous Master mode in that the shift clock is supplied externally at the CK pin (instead of being supplied internally in Master mode). This allows the device to transfer or receive data while in any low-power mode.

15.4.1 EUSART SYNCHRONOUS SLAVE TRANSMISSION

The operation of the Synchronous Master and Slave modes are identical, except in the case of the Sleep mode.

If two words are written to the TXREG and then the SLEEP instruction is executed, the following will occur:

a) The first word will immediately transfer to the TSR register and transmit.
b) The second word will remain in the TXREG register.
c) Flag bit, TXIF, will not be set.
d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit, TXIF, will now be set.
e) If enable bit, TXIE, is set, the interrupt will wake the chip from Sleep. If the global interrupt is enabled, the program will branch to the interrupt vector.

To set up a Synchronous Slave Transmission:

1. Enable the synchronous slave serial port by setting bits, SYNC and SPEN, and clearing bit, CSRC.
2. Clear bits, CREN and SREN.
3. If interrupts are desired, set enable bit, TXIE.
4. If the signal from the CK pin is to be inverted, set the TXCKP bit.
5. If 9-bit transmission is desired, set bit, TX9.
6. Enable the transmission by setting enable bit, TXEN.
7. If 9-bit transmission is selected, the ninth bit should be loaded in bit, TX9D.
8. Start transmission by loading data to the TXREG register.
9. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

TABLE 15-9: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	47
PIR1	—	ADIF	RCIF	TXIF	CMP2IF	CMP1IF	CMP0IF	TMR1IF	49
PIE1	—	ADIE	RCIE	TXIE	CMP2IE	CMP1IE	CMP0IE	TMR1IE	49
IPR1	—	ADIP	RCIP	TXIP	CMP2IP	CMP1IP	CMP0IP	TMR1IP	49
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	48
TXREG	EUSART Transmit Register								48
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	48
BAUDCON	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN	48
SPBRGH	EUSART Baud Rate Generator Register High Byte								48
SPBRG	EUSART Baud Rate Generator Register Low Byte								48

Legend: — = unimplemented, read as '0'. Shaded cells are not used for synchronous slave transmission.

16.5 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ACQT2:ACQT0 and ADCS2:ADCS0 bits in ADCON2 should be updated in accordance with the clock source to be used in that mode. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D FRC clock to be selected. If bits ACQT2:ACQT0 are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

16.6 Configuring Analog Port Pins

The ADCON1 and TRISA registers configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (V_{OH} or V_{OL}) will be converted.

The A/D operation is independent of the state of the CHS1:CHS0 bits and the TRIS bits.

Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs will convert as analog inputs. Analog levels on a digitally configured input will be accurately converted.

2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.

REGISTER 20-15: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	SWDTEN(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-1 **Unimplemented:** Read as '0'

bit 0 **SWDTEN:** Software Controlled Watchdog Timer Enable bit(1)
1 = Watchdog Timer is on
0 = Watchdog Timer is off

Note 1: This bit has no effect if the Configuration bit, WDTEN, is enabled.

TABLE 20-2: SUMMARY OF WATCHDOG TIMER REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
RCON	IPEN	SBOREN(1)	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	48
WDTCON	—	—	—	—	—	—	—	SWDTEN(2)	48

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the Watchdog Timer.

Note 1: The SBOREN bit is only available when the BOREN1:BOREN0 Configuration bits = 01; otherwise, it is disabled and reads as '0'. See **Section 5.4 "Brown-out Reset (BOR)"**.

2: This bit has no effect if the Configuration bit, WDTEN, is enabled.

20.5 Program Verification and Code Protection

The overall structure of the code protection on the PIC18 Flash devices differs significantly from other PIC® devices.

The user program memory is divided into three blocks. One of these is a Boot Block of variable size (maximum 2 Kbytes). The remainder of the memory is divided into two blocks on binary boundaries.

Each of the three blocks has three code protection bits associated with them. They are:

- Code-Protect bit (CPx)
- Write-Protect bit (WRTx)
- External Block Table Read bit (EBTRx)

Figure 20-5 shows the program memory organization for 4 and 8-Kbyte devices and the specific code protection bit associated with each block. The actual locations of the bits are summarized in Table 20-3.

FIGURE 20-5: CODE-PROTECTED PROGRAM MEMORY FOR PIC18F1230/1330

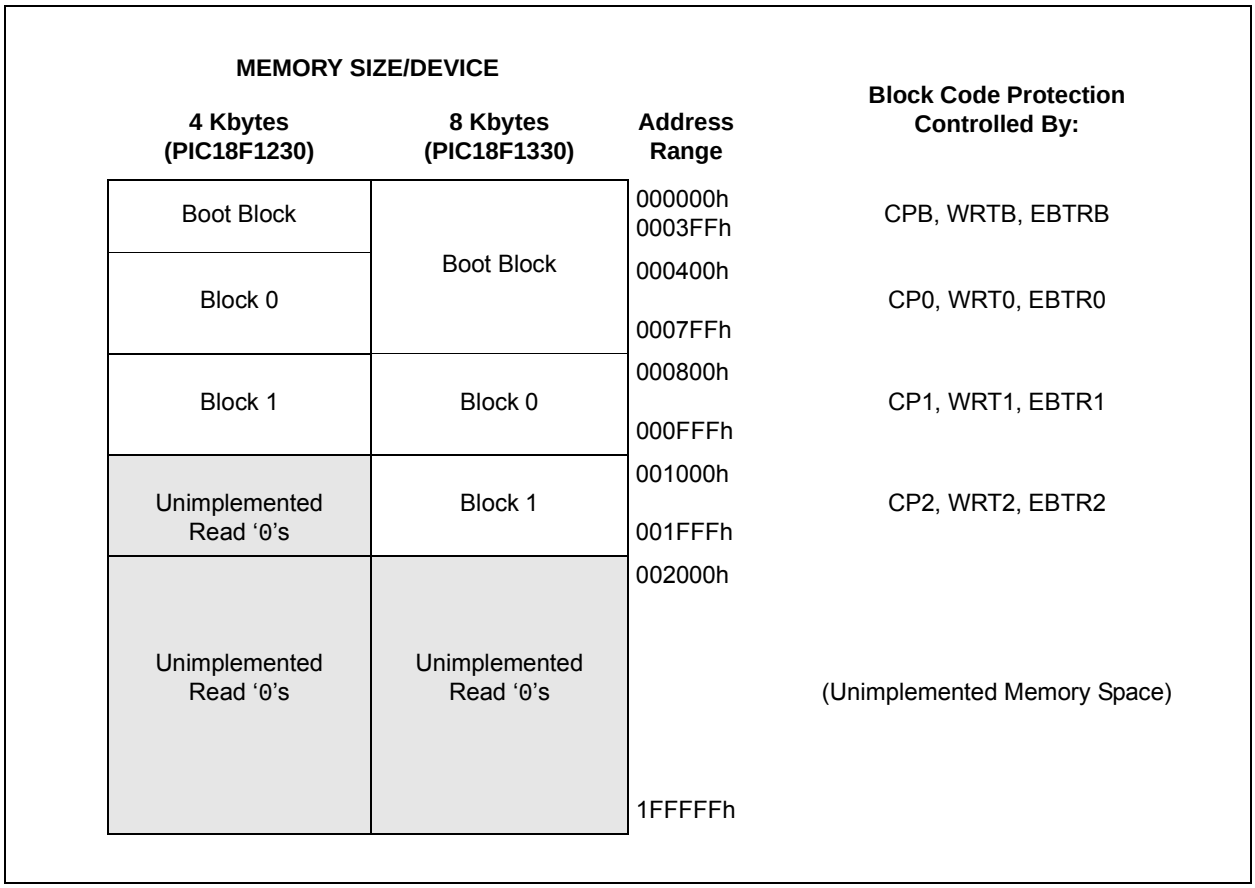


TABLE 20-3: SUMMARY OF CODE PROTECTION REGISTERS

File Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
300008h	CONFIG5L	—	—	—	—	—	—	CP1	CP0
300009h	CONFIG5H	CPD	CPB	—	—	—	—	—	—
30000Ah	CONFIG6L	—	—	—	—	—	—	WRT1	WRT0
30000Bh	CONFIG6H	WRTD	WRTB	WRTC	—	—	—	—	—
30000Ch	CONFIG7L	—	—	—	—	—	—	EBTR1	EBTR0
30000Dh	CONFIG7H	—	EBTRB	—	—	—	—	—	—

Legend: Shaded cells are unimplemented.

21.11 PICSTART Plus Development Programmer

The PICSTART Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

21.12 PICkit 2 Development Programmer

The PICkit™ 2 Development Programmer is a low-cost programmer and selected Flash device debugger with an easy-to-use interface for programming many of Microchip's baseline, mid-range and PIC18F families of Flash memory microcontrollers. The PICkit 2 Starter Kit includes a prototyping development board, twelve sequential lessons, software and HI-TECH's PICC™ Lite C compiler, and is designed to help get up to speed quickly using PIC® microcontrollers. The kit provides everything needed to program, evaluate and develop applications using Microchip's powerful, mid-range Flash memory family of microcontrollers.

21.13 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart® battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) and the latest *"Product Selector Guide"* (DS00148) for the complete list of demonstration, development and evaluation kits.

TABLE 22-2: PIC18FXXXX INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	16-Bit Instruction Word				Status Affected	Notes
				MSb			LSb		
LITERAL OPERATIONS									
ADDLW	k	Add Literal and WREG	1	0000	1111	kkkk	kkkk	C, DC, Z, OV, N	
ANDLW	k	AND Literal with WREG	1	0000	1011	kkkk	kkkk	Z, N	
IORLW	k	Inclusive OR Literal with WREG	1	0000	1001	kkkk	kkkk	Z, N	
LFSR	f, k	Move Literal (12-bit) 2nd word	2	1110	1110	00ff	kkkk	None	
		to FSR(f) 1st word		1111	0000	kkkk	kkkk		
MOVLB	k	Move Literal to BSR<3:0>	1	0000	0001	0000	kkkk	None	
MOVLW	k	Move Literal to WREG	1	0000	1110	kkkk	kkkk	None	
MULLW	k	Multiply Literal with WREG	1	0000	1101	kkkk	kkkk	None	
RETLW	k	Return with Literal in WREG	2	0000	1100	kkkk	kkkk	None	
SUBLW	k	Subtract WREG from Literal	1	0000	1000	kkkk	kkkk	C, DC, Z, OV, N	
XORLW	k	Exclusive OR Literal with WREG	1	0000	1010	kkkk	kkkk	Z, N	
DATA MEMORY ↔ PROGRAM MEMORY OPERATIONS									
TBLRD*		Table Read	2	0000	0000	0000	1000	None	
TBLRD*+		Table Read with Post-Increment		0000	0000	0000	1001	None	
TBLRD*-		Table Read with Post-Decrement		0000	0000	0000	1010	None	
TBLRD+*		Table Read with Pre-Increment		0000	0000	0000	1011	None	
TBLWT*		Table Write	2	0000	0000	0000	1100	None	
TBLWT*+		Table Write with Post-Increment		0000	0000	0000	1101	None	
TBLWT*-		Table Write with Post-Decrement		0000	0000	0000	1110	None	
TBLWT+*		Table Write with Pre-Increment		0000	0000	0000	1111	None	

Note 1: When a PORT register is modified as a function of itself (e.g., `MOVF PORTB, 1, 0`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and where applicable, 'd' = 1), the prescaler will be cleared if assigned.

3: If the Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

4: Some instructions are two-word instructions. The second word of these instructions will be executed as a `NOP` unless the first word of the instruction retrieves the information embedded in these 16 bits. This ensures that all program memory locations have a valid instruction.

DAW **Decimal Adjust W Register**

Syntax: DAW

Operands: None

Operation: If [W<3:0> > 9] or [DC = 1] then,
(W<3:0>) + 6 → W<3:0>;
else,
(W<3:0>) → W<3:0>

If [W<7:4> + DC > 9] or [C = 1] then,
(W<7:4>) + 6 + DC → W<7:4> ;
else,
(W<7:4>) + DC → W<7:4>

Status Affected: C

Encoding:

0000	0000	0000	0111

Description: DAW adjusts the eight-bit value in W resulting from the earlier addition of two variables (each in packed BCD format) and produces a correct packed BCD result.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register W	Process Data	Write W

Example 1:

```
DAW
```

Before Instruction
W = A5h
C = 0
DC = 0
After Instruction
W = 05h
C = 1
DC = 0

Example 2:

Before Instruction
W = CEh
C = 0
DC = 0
After Instruction
W = 34h
C = 1
DC = 0

DECF **Decrement f**

Syntax: DECF f {,d {,a}}

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]
a ∈ [0,1]

Operation: (f) – 1 → dest

Status Affected: C, DC, N, OV, Z

Encoding:

0000	01da	ffff	ffff

Description: Decrement register 'f'. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: DECF CNT, 1, 0

Before Instruction
CNT = 01h
Z = 0
After Instruction
CNT = 00h
Z = 1

SUBWFB **Subtract W from f with Borrow**

Syntax: SUBWFB f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) – (W) – ($\overline{C}$) → dest

Status Affected: N, OV, C, DC, Z

Encoding:

0101	10da	ffff	ffff

Description: Subtract W and the Carry flag (borrow) from register 'f' (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1:
```
SUBWFB  REG, 1, 0
Before Instruction
    REG  =  19h   (0001 1001)
    W    =  0Dh   (0000 1101)
    C    =  1
After Instruction
    REG  =  0Ch   (0000 1011)
    W    =  0Dh   (0000 1101)
    C    =  1
    Z    =  0
    N    =  0     ; result is positive
```

Example 2:
```
SUBWFB  REG, 0, 0
Before Instruction
    REG  =  1Bh   (0001 1011)
    W    =  1Ah   (0001 1010)
    C    =  0
After Instruction
    REG  =  1Bh   (0001 1011)
    W    =  00h
    C    =  1
    Z    =  1     ; result is zero
    N    =  0
```

Example 3:
```
SUBWFB  REG, 1, 0
Before Instruction
    REG  =  03h   (0000 0011)
    W    =  0Eh   (0000 1101)
    C    =  1
After Instruction
    REG  =  F5h   (1111 0100)
                  ; [2's comp]
    W    =  0Eh   (0000 1101)
    C    =  0
    Z    =  0
    N    =  1     ; result is negative
```

SWAPF **Swap f**

Syntax: SWAPF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f<3:0>) → dest<7:4>,
(f<7:4>) → dest<3:0>

Status Affected: None

Encoding:

0011	10da	ffff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in register 'f'.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example:
```
SWAPF   REG, 1, 0
Before Instruction
    REG  =  53h
After Instruction
    REG  =  35h
```

22.2 Extended Instruction Set

In addition to the standard 75 instructions of the PIC18 instruction set, PIC18F1230/1330 devices also provide an optional extension to the core CPU functionality. The added features include eight additional instructions that augment indirect and indexed addressing operations and the implementation of Indexed Literal Offset Addressing mode for many of the standard PIC18 instructions.

The additional features of the extended instruction set are disabled by default. To enable them, users must set the XINST Configuration bit.

The instructions in the extended set (with the exception of CALLW, MOVSF and MOVSS) can all be classified as literal operations, which either manipulate the File Select Registers, or use them for indexed addressing. Two of the instructions, ADDFSR and SUBFSR, each have an additional special instantiation for using FSR2. These versions (ADDULNK and SUBULNK) allow for automatic return after execution.

The extended instructions are specifically implemented to optimize re-entrant program code (that is, code that is recursive or that uses a software stack) written in high-level languages, particularly C. Among other things, they allow users working in high-level languages to perform certain operations on data structures more efficiently. These include:

- Dynamic allocation and deallocation of software stack space when entering and leaving subroutines
- Function Pointer invocation
- Software Stack Pointer manipulation
- Manipulation of variables located in a software stack

A summary of the instructions in the extended instruction set is provided in Table 22-3. Detailed descriptions are provided in **Section 22.2.2 "Extended Instruction Set"**. The opcode field descriptions in Table 22-1 (page 216) apply to both the standard and extended PIC18 instruction sets.

Note:	The instruction set extension and the Indexed Literal Offset Addressing mode were designed for optimizing applications written in C; the user may likely never use these instructions directly in the assembler. The syntax for these commands is provided as a reference for users who may be reviewing code that has been generated by a compiler.

22.2.1 EXTENDED INSTRUCTION SYNTAX

Most of the extended instructions use indexed arguments, using one of the File Select Registers and some offset to specify a source or destination register. When an argument for an instruction serves as part of indexed addressing, it is enclosed in square brackets ("[ ]"). This is done to indicate that the argument is used as an index or offset. The MPASM™ Assembler will flag an error if it determines that an index or offset value is not bracketed.

When the extended instruction set is enabled, brackets are also used to indicate index arguments in byte-oriented and bit-oriented instructions. This is in addition to other changes in their syntax. For more details, see **Section 22.2.3.1 "Extended Instruction Syntax with Standard PIC18 Commands"**.

Note:	In the past, square brackets have been used to denote optional arguments in the PIC18 and earlier instruction sets. In this text and going forward, optional arguments are denoted by braces ("{ }").

TABLE 22-3: EXTENSIONS TO THE PIC18 INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	16-Bit Instruction Word				Status Affected
				MSb			LSb	
ADDFSR	f, k	Add Literal to FSR	1	1110	1000	ffkk	kkkk	None
ADDULNK	k	Add Literal to FSR2 and Return	2	1110	1000	11kk	kkkk	None
CALLW		Call Subroutine using WREG	2	0000	0000	0001	0100	None
MOVSF	z_s, f_d	Move z_s (source) to 1st word f_d (destination) 2nd word	2	1110 1111	1011 ffff	0zzz ffff	zzzz ffff	None
MOVSS	z_s, z_d	Move z_s (source) to 1st word z_d (destination) 2nd word	2	1110 1111	1011 xxxx	1zzz xzzz	zzzz zzzz	None
PUSHL	k	Store Literal at FSR2, Decrement FSR2	1	1110	1010	kkkk	kkkk	None
SUBFSR	f, k	Subtract Literal from FSR	1	1110	1001	ffkk	kkkk	None
SUBULNK	k	Subtract Literal from FSR2 and Return	2	1110	1001	11kk	kkkk	None

23.3 DC Characteristics: PIC18F1230/1330 (Industrial) PIC18LF1230/1330 (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended			
Param No.	**Symbol**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**				
		I/O ports:				
D030		with TTL buffer	VSS	0.15 VDD	V	VDD < 4.5V
D030A			—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D031		with Schmitt Trigger buffer	VSS	0.2 VDD	V	
D031A		RC3 and RC4	VSS	0.3 VDD	V	I²C™ enabled
D031B			VSS	0.8	V	SMBus enabled
D032		$\overline{MCLR}$	VSS	0.2 VDD	V	
D033		OSC1	VSS	0.3 VDD	V	HS, HSPLL modes
D033A		OSC1	VSS	0.2 VDD	V	RC, EC modes(1)
D033B		OSC1	VSS	0.3	V	XT, LP modes
D034		T1CKI	VSS	0.3	V	
	VIH	**Input High Voltage**				
		I/O ports:				
D040		with TTL buffer	0.25 VDD + 0.8V	VDD	V	VDD < 4.5V
D040A			2.0	VDD	V	4.5V ≤ VDD ≤ 5.5V
D041		with Schmitt Trigger buffer	0.8 VDD	VDD	V	
D041A		RC3 and RC4	0.7 VDD	VDD	V	I²C enabled
D041B			2.1	VDD		I²C enabled
D042		$\overline{MCLR}$	0.8 VDD	VDD	V	
D043		OSC1	0.7 VDD	VDD	V	HS, HSPLL modes
D043A		OSC1	0.8 VDD	VDD	V	EC mode
D043B		OSC1	0.9 VDD	VDD	V	RC mode(1)
D043C		OSC1	1.6	VDD	V	XT, LP modes
D044		T1CKI	1.6	VDD	V	
	IIL	**Input Leakage Current(2,3)**				
D060		I/O ports	—	±200	nA	VSS < 5.5V Vss ≤ VPIN ≤ VDD Pin at high-impedance
				±50	nA	VSS < 3V Vss ≤ VPIN ≤ VDD Pin at high-impedance
D061		$\overline{MCLR}$	—	±1	µA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	±1	µA	Vss ≤ VPIN ≤ VDD
	IPU	**Weak Pull-up Current**				
D070	IPURB	PORTB weak pull-up current	50	400	µA	VDD = 5V, VPIN = VSS

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

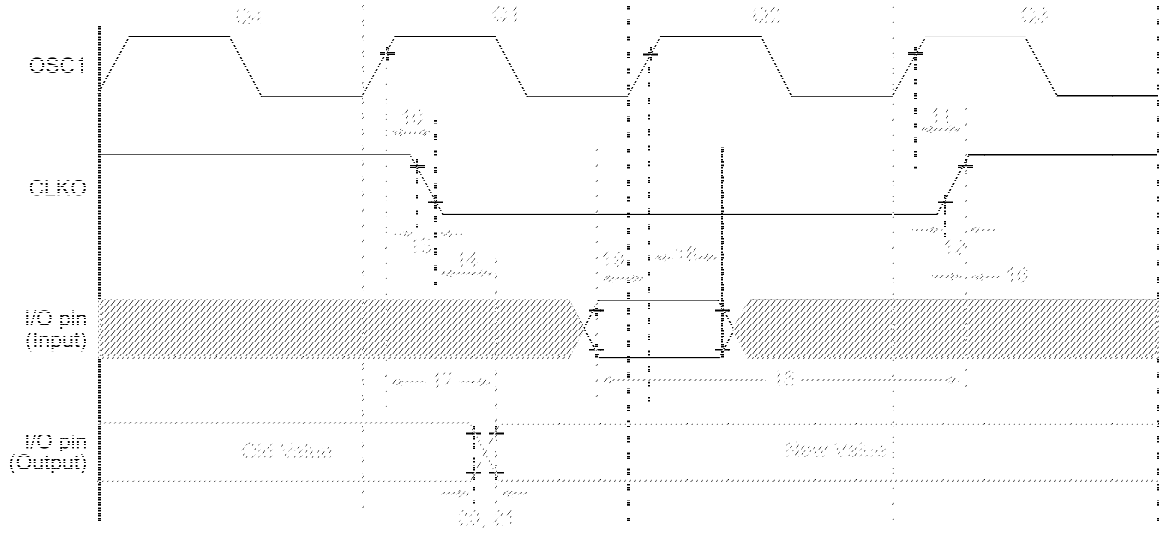
TABLE 23-1: MEMORY PROGRAMMING REQUIREMENTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Data EEPROM Memory					
D120	ED	Byte Endurance	100K	1M	—	E/W	-40°C to +85°C
D121	VDRW	VDD for Read/Write	VMIN	—	5.5	V	Using EECON to read/write VMIN = Minimum operating voltage
D122	TDEW	Erase/Write Cycle Time	3.59	4.10	4.86	ms	
D123	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D124	TREF	Number of Total Erase/Write Cycles before Refresh(1)	1M	10M	—	E/W	-40°C to +85°C
D125	IDDP	Supply Current during Programming	—	10	—	mA	
		Program Flash Memory					
D130	EP	Cell Endurance	10K	100K	—	E/W	-40°C to +85°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132B	VPEW	VDD for Self-Timed Write	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D133A	TIW	Self-Timed Write Cycle Time	1.79	2.05	2.43	ms	
D134	TRETD	Characteristic Retention	40	100	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Refer to Section 7.8 for a more detailed discussion on data EEPROM endurance.

FIGURE 23-7: CLKO AND I/O TIMING



Note: Refer to Figure 23-5 for load conditions.

TABLE 23-9: CLKO AND I/O TIMING REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ	Max	Units	Conditions
10	TosH2ckL	OSC1 ↑ to CLKO ↓		—	75	200	ns	**(Note 1)**
11	TosH2ckH	OSC1 ↑ to CLKO ↑		—	75	200	ns	**(Note 1)**
12	TckR	CLKO Rise Time		—	35	100	ns	**(Note 1)**
13	TckF	CLKO Fall Time		—	35	100	ns	**(Note 1)**
14	TckL2ioV	CLKO ↓ to Port Out Valid		—	—	0.5 TCY + 20	ns	**(Note 1)**
15	TioV2ckH	Port In Valid before CLKO ↑		0.25 TCY + 25	—	—	ns	**(Note 1)**
16	TckH2ioI	Port In Hold after CLKO ↑		0	—	—	ns	**(Note 1)**
17	TosH2ioV	OSC1 ↑ (Q1 cycle) to Port Out Valid		—	50	150	ns	
18	TosH2ioI	OSC1 ↑ (Q2 cycle) to Port Input Invalid (I/O in hold time)	PIC18**F**XXXX	100	—	—	ns	
18A			PIC18**LF**XXXX	200	—	—	ns	VDD = 2.0V
19	TioV2osH	Port Input Valid to OSC1 ↑ (I/O in setup time)		0	—	—	ns	
20	TioR	Port Output Rise Time	PIC18**F**XXXX	—	10	25	ns	
20A			PIC18**LF**XXXX	—	—	60	ns	VDD = 2.0V
21	TioF	Port Output Fall Time	PIC18**F**XXXX	—	10	25	ns	
21A			PIC18**LF**XXXX	—	—	60	ns	VDD = 2.0V
22†	TINP	INTx Pin High or Low Time		TCY	—	—	ns	
23†	TRBP	RB7:RB4 Change INTx High or Low Time		TCY	—	—	ns	

† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC mode, where CLKO output is 4 x TOSC.